

ABSTRACT OF THE INVENTION

A protection structure for a thermal conducting medium of a heat dissipation structure installed on the heat dissipation device at the position on which the thermal conducting medium is coated. The protection structure has a bottom
5 surface to cover the thermal conducting medium, a side wall extending along and projecting from a periphery of the bottom surface to form a space for receiving the thermal conducting medium and a portion of the heat dissipation device, and a support structure protruding from the bottom surface to avoid a direct contact between the thermal conducting medium and the bottom surface.